Special Issue

Image/Signal Processing and Machine Vision in Security and Industrial Applications

Message from the Guest Editors

Machine vision utilizes industrial image processing through the use of cameras in order to visually inspect products, or guide robots in real time automatically. Machine vision and image processing technologies are widely employed in security screening and industrial inspection. This Special Issue intends to provide a timely chance to scientists, researchers, as well as engineers to discuss and summarize the latest signal/image processing and machine vision methods in security and industrial applications. We invite papers that include but are not exclusive to the following topics: artificial intelligence, pattern recognition/analysis technologies in human analysis, behavior understanding, and biometrics for security application, intelligent transportation system based on computer vision methods, robotics and intelligent systems, pose recognition of industrial products...Both theoretical and experimental studies are welcome, as well as comprehensive review and survey papers.
If you are interested, you can submit directly via the link below:
https://susy.mdpi.com/user/manuscripts/upload?form[journal_id]=90&form[special_issue_id]=91750

Guest Editors

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Deadline for manuscript submissions

closed (30 April 2022)

Applied Sciences

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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